

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Accompanying Divisional Application Under
37 CFR 1.53(b) :

Prior Application: A. IWAYA et al
 Serial No. 09/563,455
 Filed: May 3, 2000

Group Art Unit: 2811
Examiner: L. Thai
For: A SEMICONDUCTOR DEVICE

PRELIMINARY AMENDMENT

Assistant Commissioner of Patents
Washington, D.C. 20231

December 21, 2001

Sir:

Prior to examination, please amend the above application
as follows.

IN THE SPECIFICATION

Page 1, before the first line, add the paragraph:

This is a divisional application of U.S. Serial
No. 09/563,455 filed May 3, 2000.

IN THE CLAIMS

Cancel claims 1-18 without prejudice or disclaimer, and
add new claims 19-20, as follows:

19. (New) A method of manufacturing a semiconductor device comprising the steps of:

providing a wiring substrate having a main surface, a rear surface opposed to the main surface, a first row of electrode pads on the main surface, a plurality of lands formed on the rear surface and a plurality of wirings electrically connected to the electrode pads with the lands, respectively;

providing a first and a second semiconductor chip each having a main surface, a rear surface opposed to the main surface and a plurality of electrode pads formed on the main surface;

mounting the first and the second semiconductor chips on the main surface of the wiring substrate, wherein the rear surfaces of each of the semiconductor chips are facing to the main surface of the wiring substrate, and wherein the second semiconductor chip is positioned at the opposed side from the first semiconductor chip of the first row of electrode pads;

electrically connecting the electrode pads of the first semiconductor chip with the first row of electrode pads through a plurality of wires, each wire applying a first bonding to an electrode pad of the wiring substrate and a second bonding to an electrode pad of the first semiconductor chip after the first bonding; and

sealing the first and second semiconductor chips and the wires by sealing material.

20. (New) A method of manufacturing a semiconductor device according to claim 19, wherein:


the wiring substrate has a second row of electrode pads formed on the main surface of the wiring substrate, between the first semiconductor chip and the second semiconductor chip in plan; and

further comprising a step of electrically connecting the electrode pads of the second semiconductor chip with the second row of electrode pads through a plurality of wires, each wire applying a first bonding to an electrode pad of the wiring substrate and a second bonding to an electrode pad of the first semiconductor chip after the first bonding.

REMARKS

The Applicants request entry of the foregoing amendment and new claims.

Respectfully submitted,



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